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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Applicant: Young-Joon Park, et al. Docket Number: TI-35623

Serial No.: 10/628,198 Art Unit: 2814

Filed: 07/28/03 Examiner: Ginette Peralta

For: A Two-Step Semiconductor Manufacturing Process for
Copper Interconnects

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NAME OF INVENTOR(S):	
Young-Joon Park, et al.	
TITLE OF INVENTION: A Two-Step Semiconductor Manufacturing Process for Copper Interconnects	
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TI-35623	20-0668
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In re the Application of: Park et al.

Docket No.: TI-35623

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Art Unit: 2814

Filed: 07/28/2003

Examiner: Peralta, Ginette

Title: A Two-Step Semiconductor Manufacturing Process for Copper
Interconnects

AMENDMENT UNDER 37 C.F.R. §1.111

December 22, 2005

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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Karen Vertz
Karen Vertz

12-22-05
Date

Dear Commissioner:

In response to the Office Action, dated 10/05/2005, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Please charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.